



40V N&P-Channel Trench Power MOSFET

General Description

The SJG40NP790 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

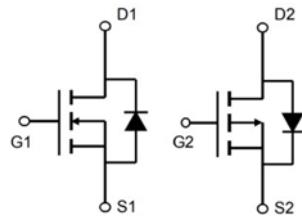
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

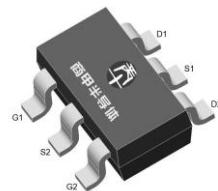
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Key Performance Parametes

Parameter	Value	Value	Unit
V_{DS}	40	-40	V
$R_{DS(ON)}_{TYP}$	23	56.7	$m\Omega$
I_D	5.5	-3.5	A
Q_G	14	11	nC



Schematic Diagram



SOT23-6L top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJG40NP790	SJG40NP790	SOT23-6L	Tape	\	\	3000 Pcs

Table 1. Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	N Limit	P Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	40	-40	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	± 20	V
I_D	Drain Current-Continuous($T_A=25^\circ C$)	5.5	-3.5	A
	Drain Current-Continuous($T_A=100^\circ C$)	3.5	-2.2	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	22	-14	A
P_D	Maximum Power Dissipation($T_A=25^\circ C$)	1.5	1.5	W
	Maximum Power Dissipation($T_A=100^\circ C$)	0.6	0.6	W
E_{AS}	Avalanche energy (Note 2)	25	25	mJ
T_J , T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150		°C

Table 2. Thermal Characteristic

Symbol	Parameter	N Limit	P Limit	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to- Ambient	85	85	°C/W



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Table 3. N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_{\text{D}}=250\mu\text{A}$	40			V
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=25^\circ\text{C}$			1	μA
		$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$			100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=250\mu\text{A}$	1		2.5	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=3\text{A}$		6.1		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=3\text{A}$ $T_J=25^\circ\text{C}$		23	28.8	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2\text{A}$ $T_J=25^\circ\text{C}$		30.3	40.3	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$		631		pF
C_{oss}	Output Capacitance			54		pF
C_{rss}	Reverse Transfer Capacitance			39		pF
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1.0\text{MHz}$		1.6		Ω
Switching Parameters						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=20\text{V}$, $R_L=5\Omega$, $R_{\text{GEN}}=3\Omega$		6		nS
t_r	Turn-on Rise Time			4		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			20		nS
t_f	Turn-Off Fall Time			3		nS
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=20\text{V}$, $I_{\text{D}}=3\text{A}$		14		nC
Q_{gs}	Gate-Source Charge			2.5		nC
Q_{gd}	Gate-Drain Charge			3		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				5.5	A
V_{SD}	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=3\text{A}$			1.2	V
t_{rr}	Reverse Recovery Time	$I_F=3\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		9		ns
Q_{rr}	Reverse Recovery Charge	$I_F=3\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		4		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

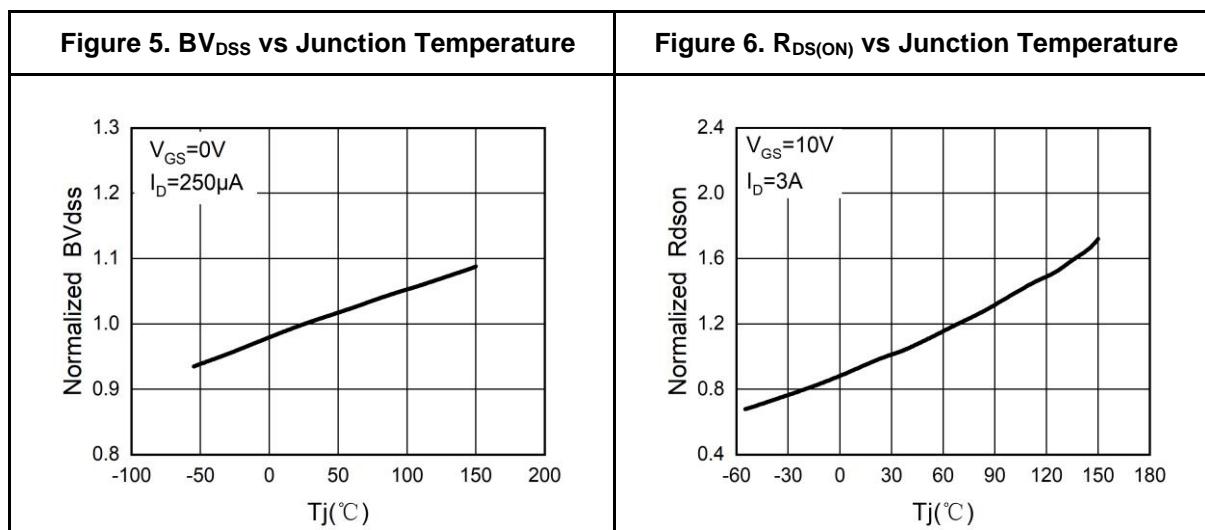
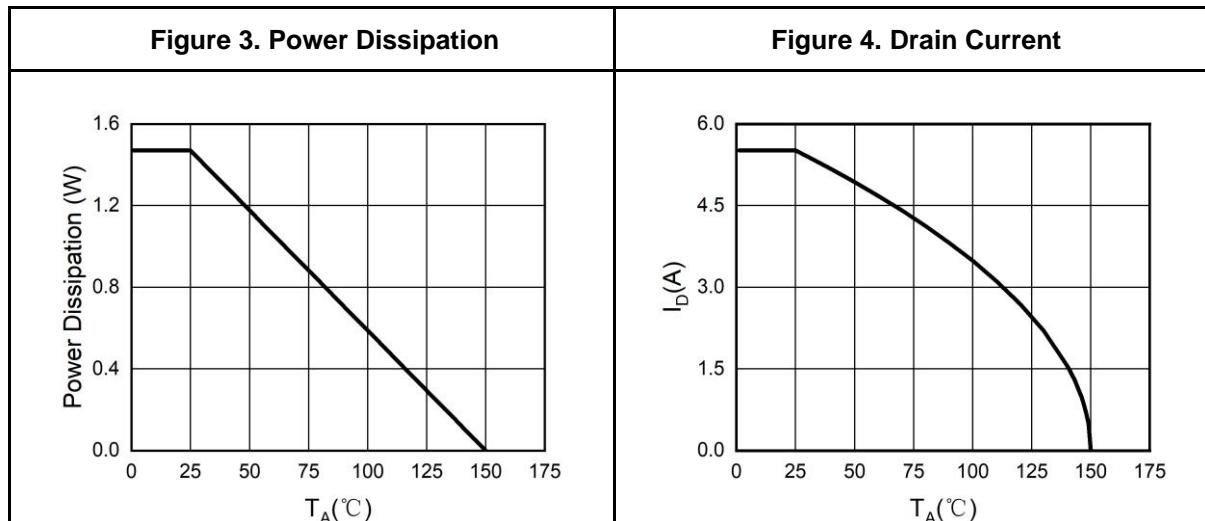
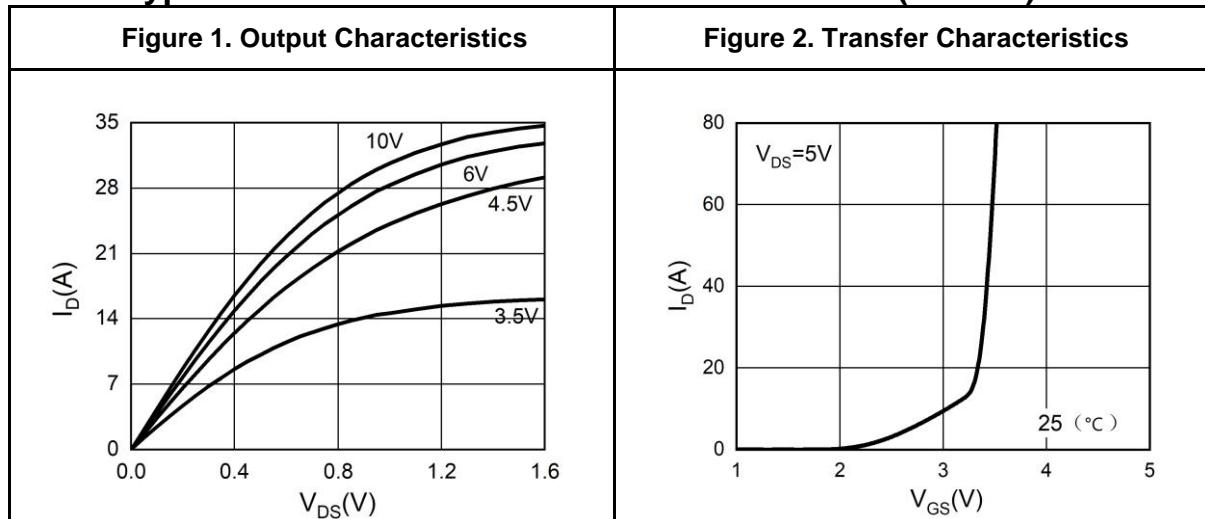
Notes 2.E_{AS} condition: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=40\text{V}$, $V_G=10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.

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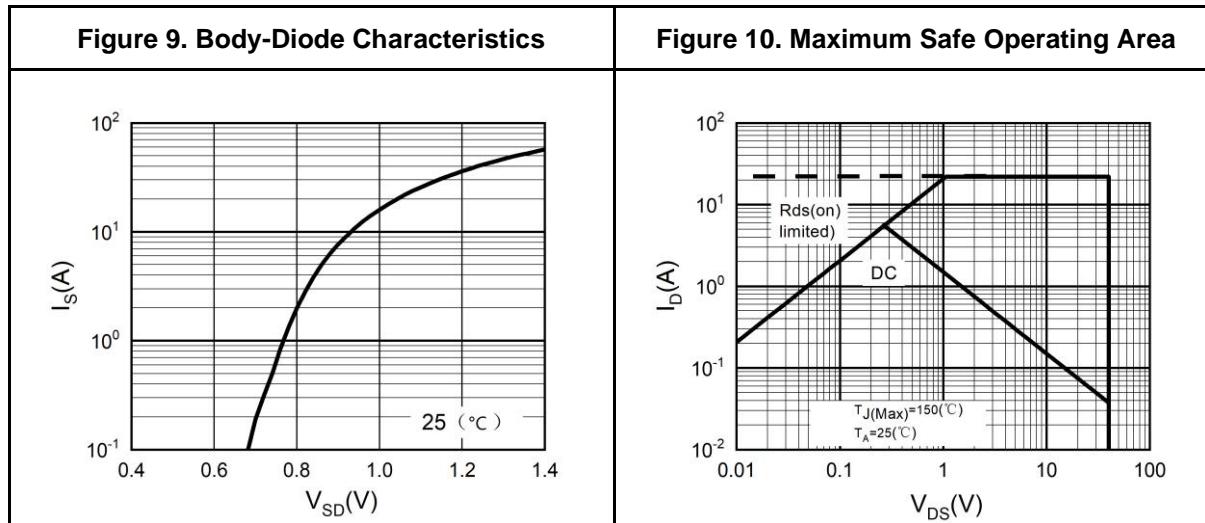
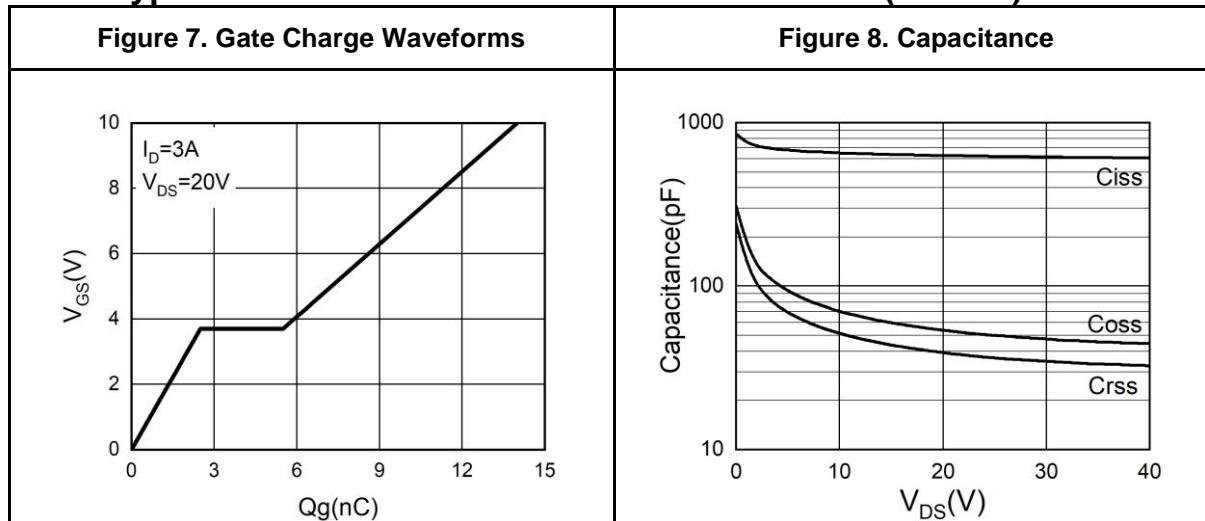
N-Channel Typical Electrical And Thermal Characteristics (Curves)





40V N&P-Channel Trench Power MOSFET

N-Channel Typical Electrical And Thermal Characteristics (Curves)





40V N&P-Channel Trench Power MOSFET

Table 4. P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_{\text{D}}=250\mu\text{A}$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-40\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=25^\circ\text{C}$			-1	μA
		$V_{\text{DS}}=-40\text{V}$, $V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$			-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=250\mu\text{A}$	-1		-2.5	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-2\text{A}$		4.1		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-2\text{A}$ $T_J=25^\circ\text{C}$		56.7	70.9	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-1.5\text{A}$ $T_J=25^\circ\text{C}$		72.8	96.8	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$		503		pF
C_{oss}	Output Capacitance			54		pF
C_{rss}	Reverse Transfer Capacitance			41		pF
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1.0\text{MHz}$		7		Ω
Switching Parameters						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=-10\text{V}$, $V_{\text{DS}}=-20\text{V}$, $R_L=10\Omega$, $R_{\text{GEN}}=3\Omega$		8		nS
t_r	Turn-on Rise Time			13		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			16		nS
t_f	Turn-Off Fall Time			6		nS
Q_g	Total Gate Charge	$V_{\text{GS}}=-10\text{V}$, $V_{\text{DS}}=-20\text{V}$, $I_{\text{D}}=-2\text{A}$		11		nC
Q_{gs}	Gate-Source Charge			1.8		nC
Q_{gd}	Gate-Drain Charge			2		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-3.5	A
V_{SD}	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-2\text{A}$			-1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=-2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		10		ns
Q_{rr}	Reverse Recovery Charge	$I_{\text{F}}=-2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		5		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

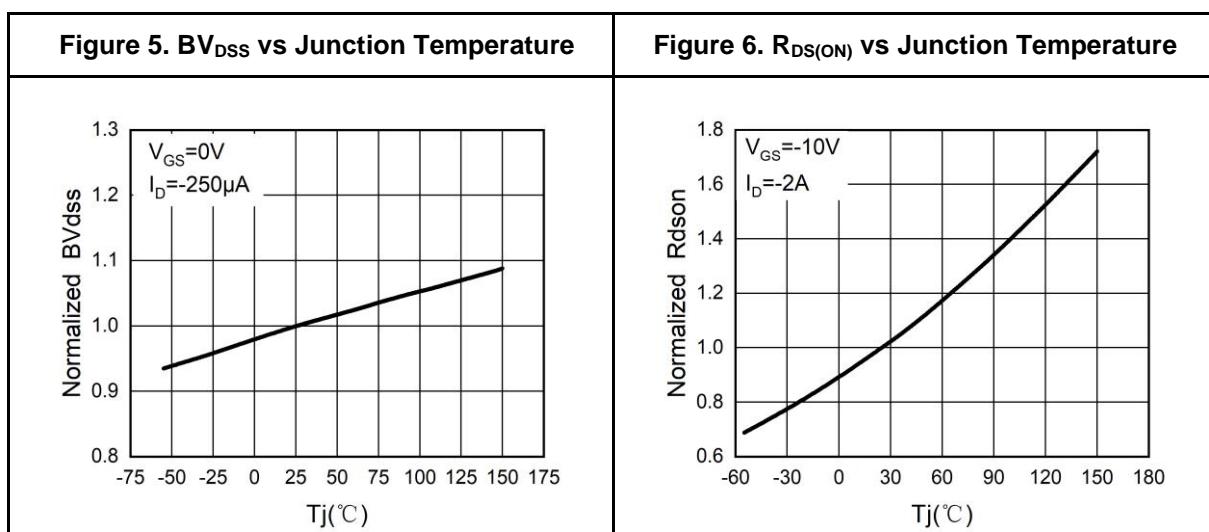
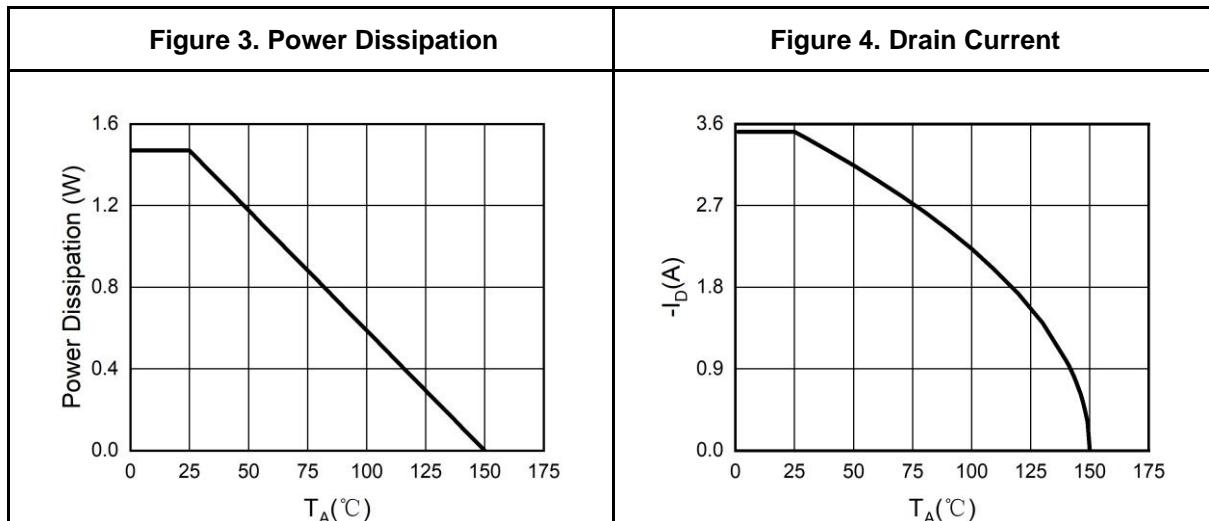
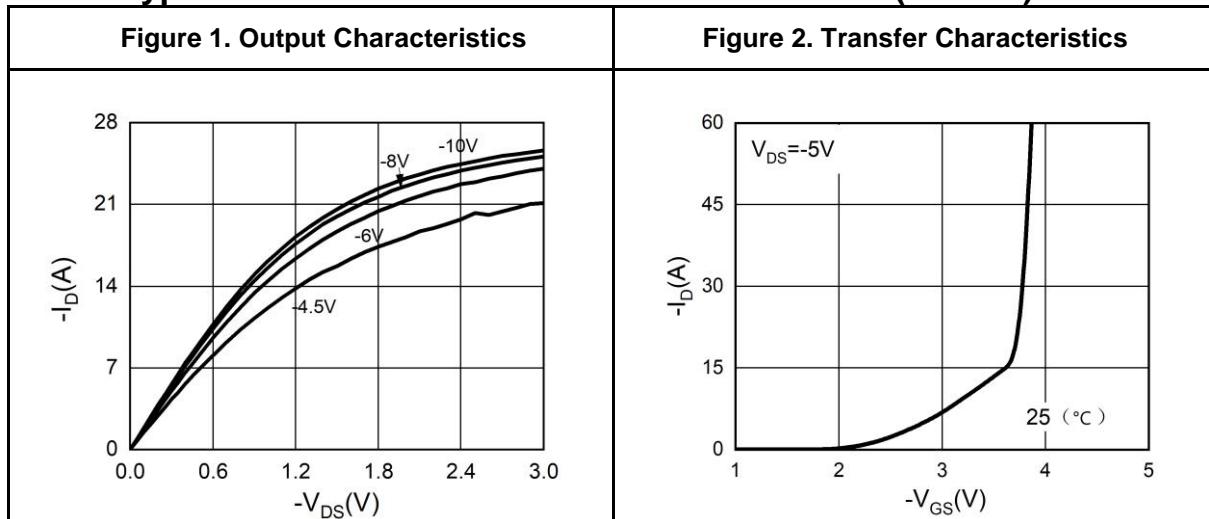
Notes 2.EAS condition: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=-40\text{V}$, $V_G=10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.

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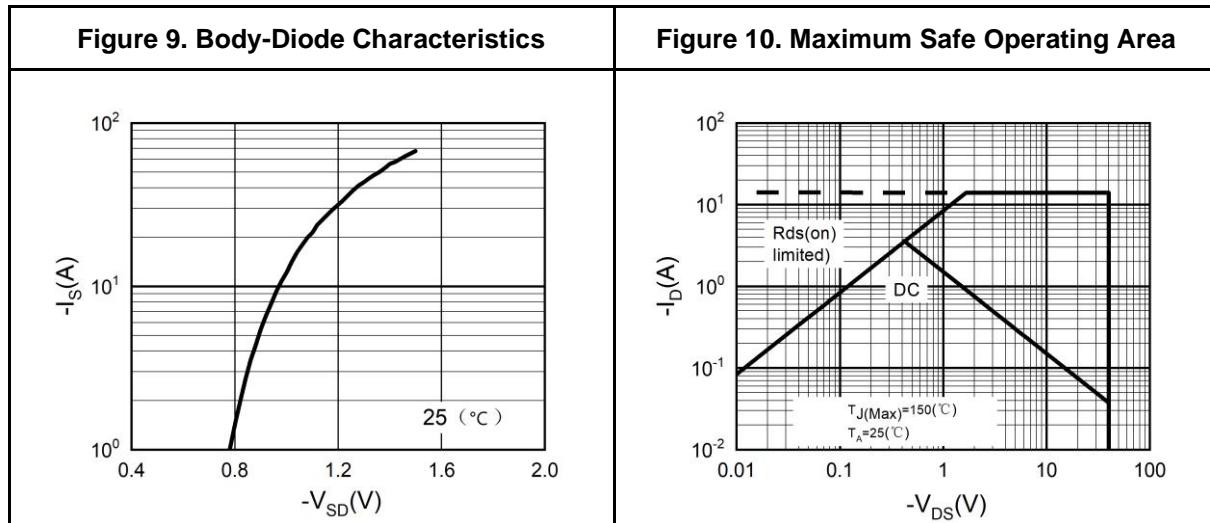
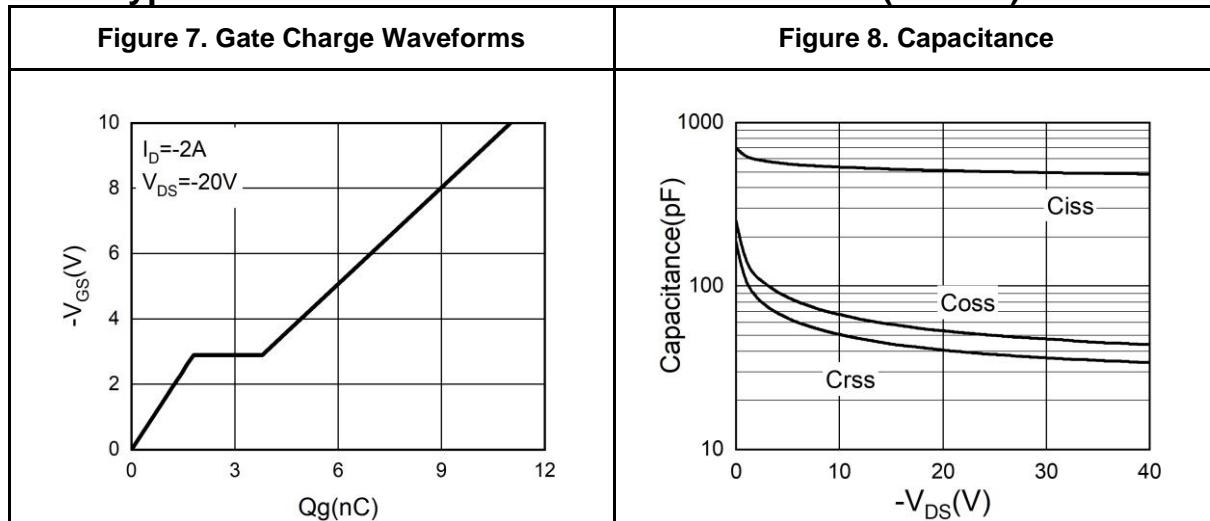
P-Channel Typical Electrical And Thermal Characteristics (Curves)





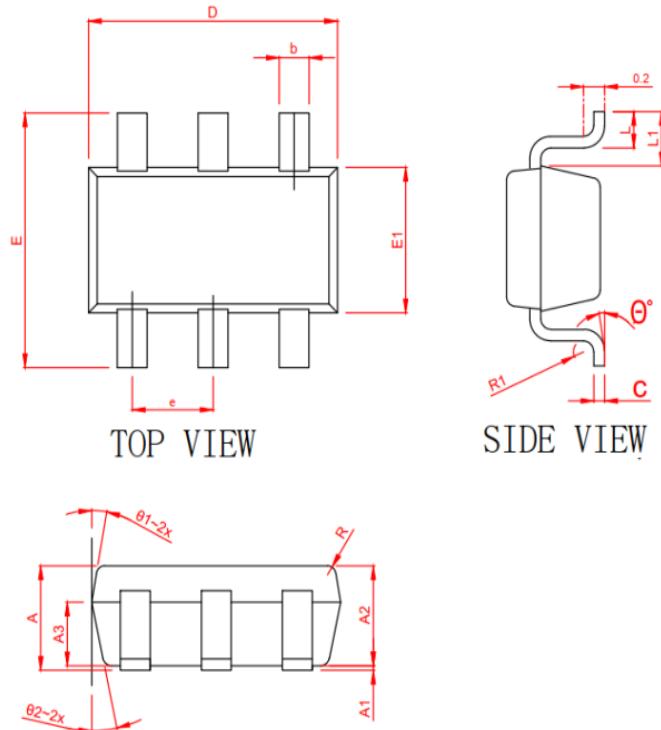
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P-Channel Typical Electrical And Thermal Characteristics (Curves)





SOT23-6L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.06	1.15	1.24
* A1	0.01	0.05	0.09
* A2	1.05	1.10	1.15
A3	0.65	0.70	0.75
* b	0.30	0.35	0.45
* c	0.127REF		
* D	2.87	2.92	2.97
* E	2.72	2.80	2.88
* E1	1.55	1.60	1.65
* e	0.95BSC		
* L	0.32	0.40	0.48
* L1	0.55	0.60	0.65
R	0.10 REF		
R1	0.12 REF		
* θ	0	--	8°
θ1	8°	10°	12°
θ2	10°	12°	14°



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Attention

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